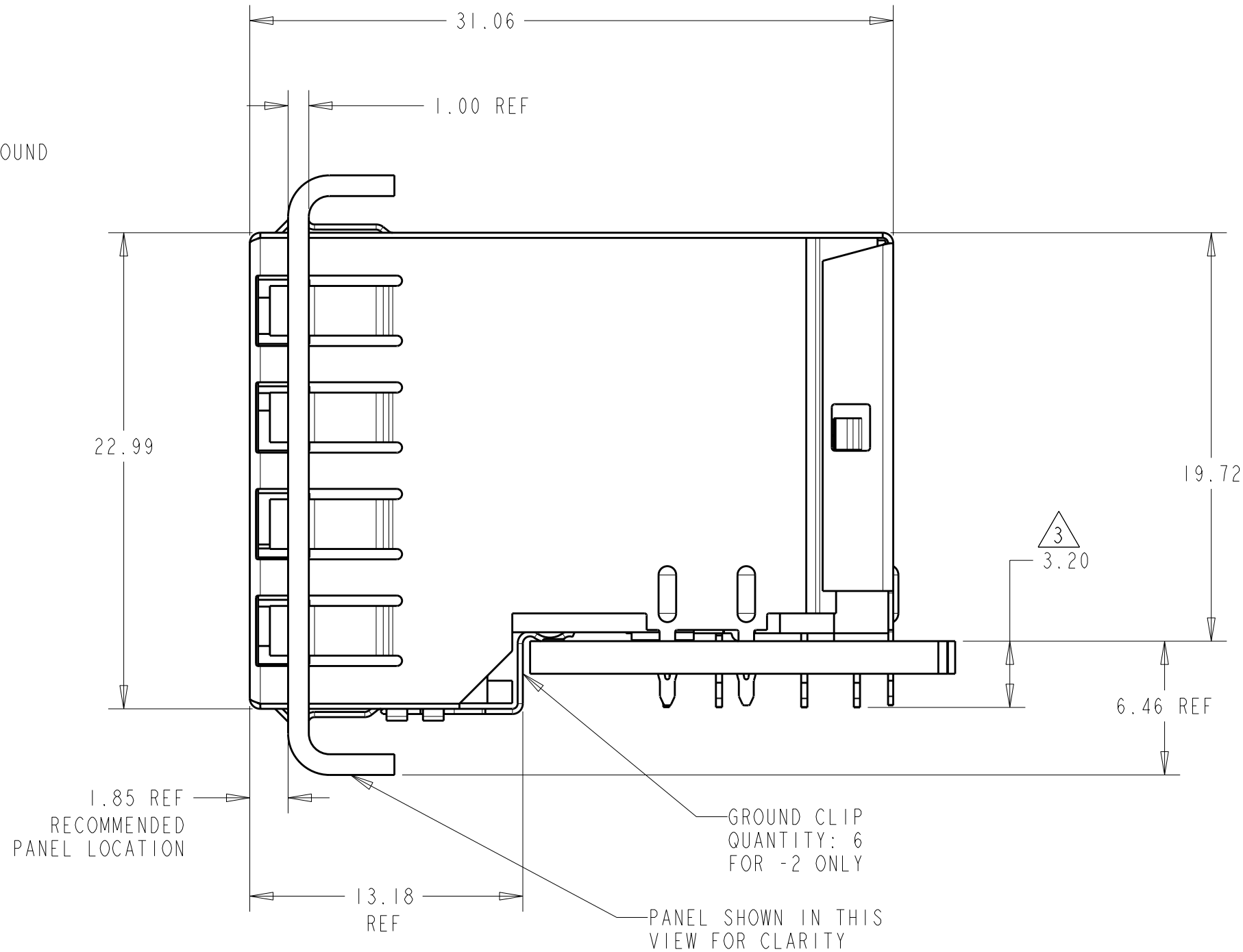
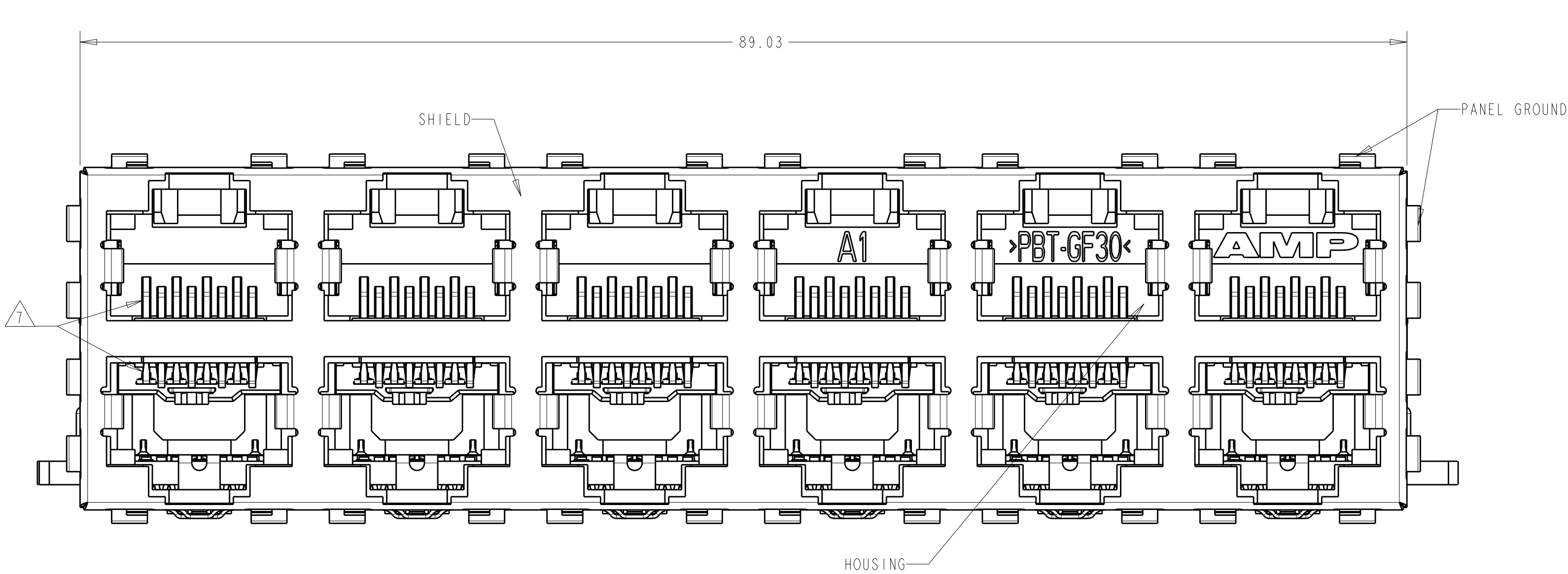


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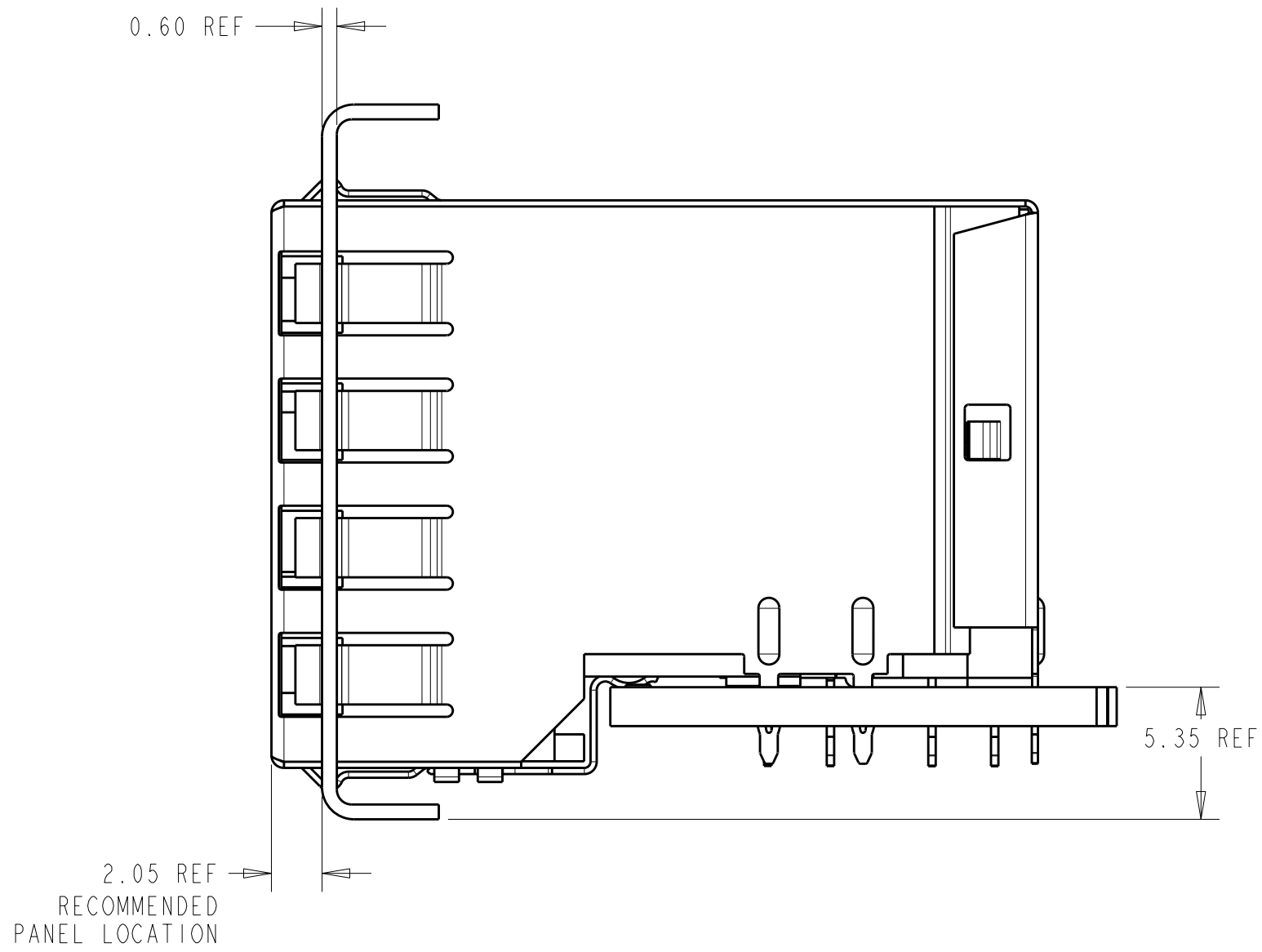
C

B

A

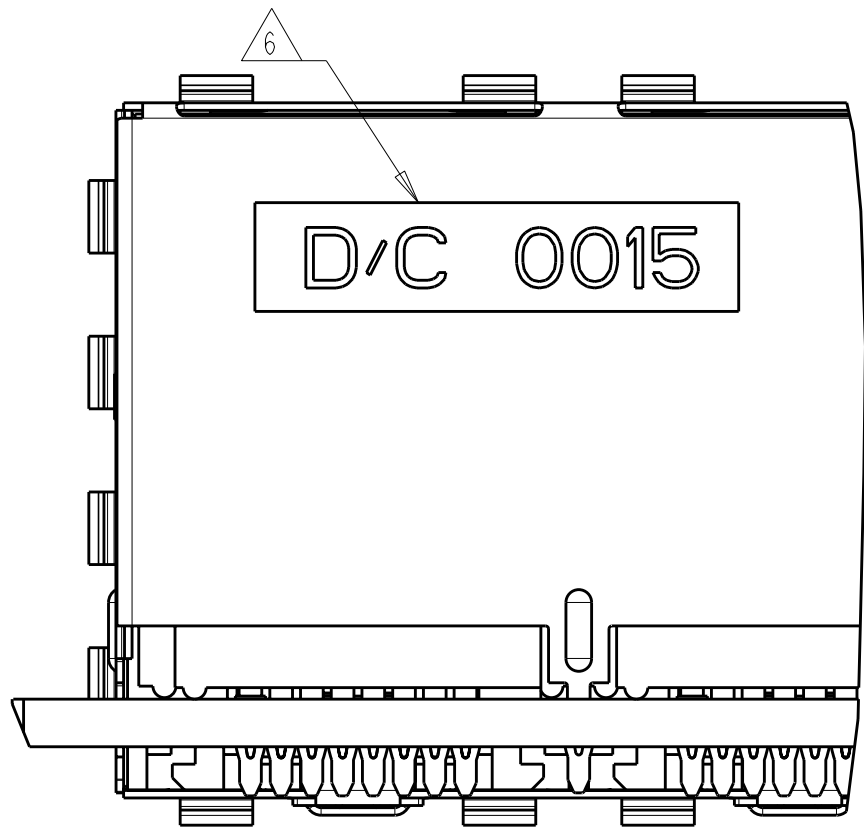


ATCA PANEL AND
PRINTED CIRCUIT BOARD
ASSEMBLY LAYOUT



AMC PANEL AND
PRINTED CIRCUIT BOARD
ASSEMBLY LAYOUT

LOC		DIST		REVISIONS					
AA		00		P	LYR	DESCRIPTION	DATE	DWN	APVD
					A	RELEASED	27OCT2006	LAM	JW
					B	ECO-07-001858	31JAN2007	LAM	JW
					C	ECR-08-020353	13AUG2008	AL	SY



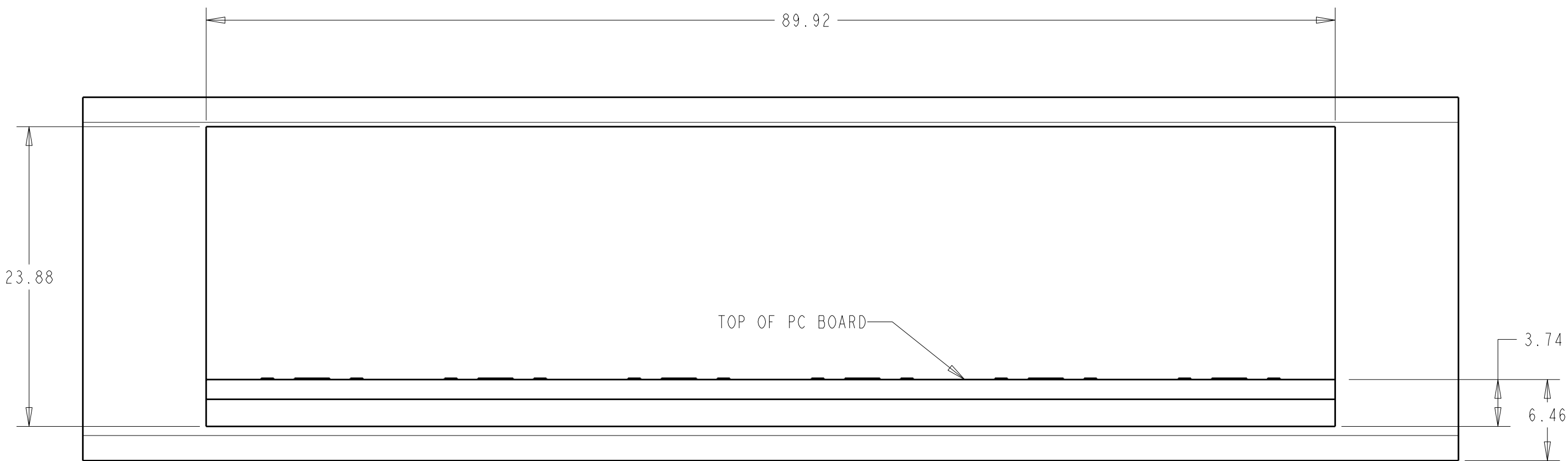
- MATERIAL:
HOUSING:
PBT POLYESTER, BLACK, UL 94V-0
TERMINALS:
0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm MINIMUM THICK
HARD GOLD IN LOCALIZED AREA AND 2.0µm MINIMUM THICK
MATTE TIN IN COMPLIANT PIN TERMINAL AREA
OVER 1.27µm MINIMUM THICK NICKEL UNDERPLATE
SHIELD:
0.25 THICK COPPER ALLOY PLATED WITH 2.03µm MINIMUM TIN
OVER 1.27 µm MINIMUM NICKEL
GROUND CLIP: 0.25 THICK COPPER ALLOY PRE-PLATED WITH 2.03µm
MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68
SUBPART F.

- MAXIMUM PIN LENGTH 3.40 FROM TOP SURFACE OF PC BOARD
- FINISHED PLATED THROUGH HOLE DIAMETER - ANNULAR RING
DIAMETER 1.3 TO 1.5
- DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
- DATE CODE LOCATED ON REAR OF PART APPROXIMATELY AS SHOWN
- CONTACTS ARE NOT INTENDED TO BE ALIGNED WITH EACH OTHER

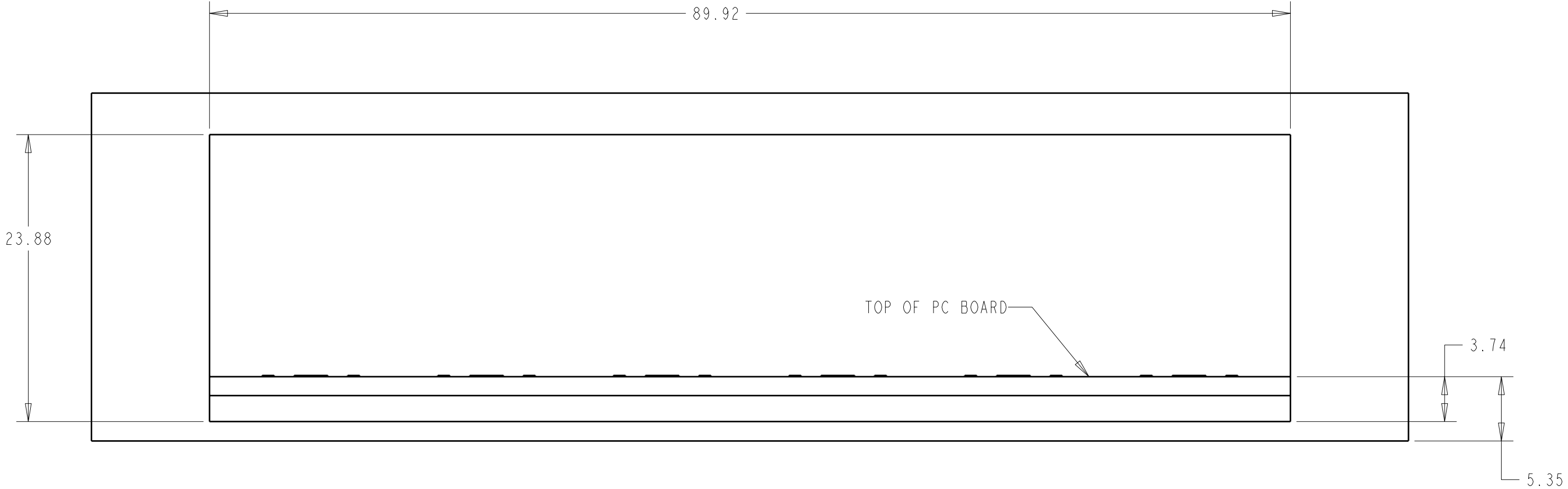
15.88	WITH GROUND CLIP	1888508-2
16.13	WITHOUT GROUND CLIP	1888508-1
M DIM	DESCRIPTION	PART NUMBER

TYPICAL DIMENSIONS TO CHANNELS TO CENTER FOR THIS ELECTRONIC CORPORATION TYPICAL DIMENSIONS TO CHANNELS TO CENTER FOR THIS ELECTRONIC CORPORATION TYPICAL DIMENSIONS TO CHANNELS TO CENTER FOR THIS ELECTRONIC CORPORATION		DWN L.A.MAYER 25OCT2006	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm		CHK J.WESTMAN 25OCT2006	NAME STACKED MODULAR JACK ASSEMBLY, 2 X 6, 8 POSN, RJ45, SHIELDED, PANEL GROUND, OFFSET, CAT 5	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S.FLICKINGER 25OCT2006	PRODUCT SPEC 108-1854	
9 PLC ± 1 PLC ± 3 PLC ±0.13 5 PLC ± 4 PLC ±		APPLICATION SPEC 114-2160	SIZE A1 00779	
MATERIAL SEE NOTE 1		WEIGHT -	CAGE CODE C=1888508	
FINISH SEE NOTE 1		CUSTOMER DRAWING	RESTRICTED TO -	
		SCALE 4:1	SHEET 1 OF 2	
			REV C	

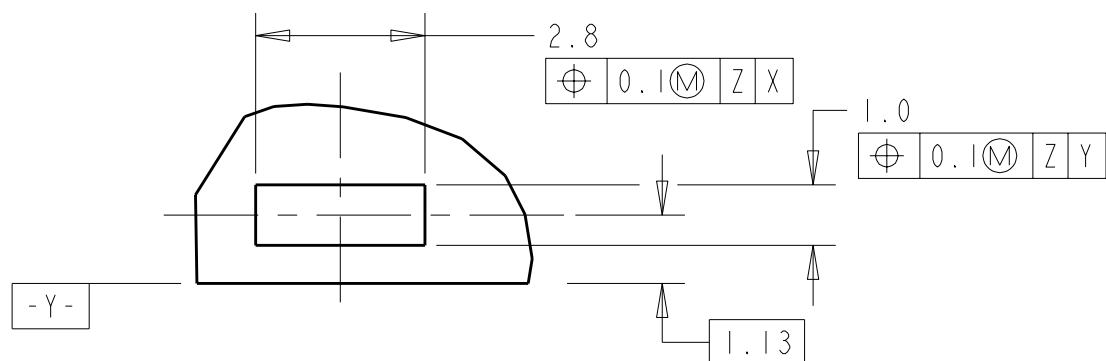
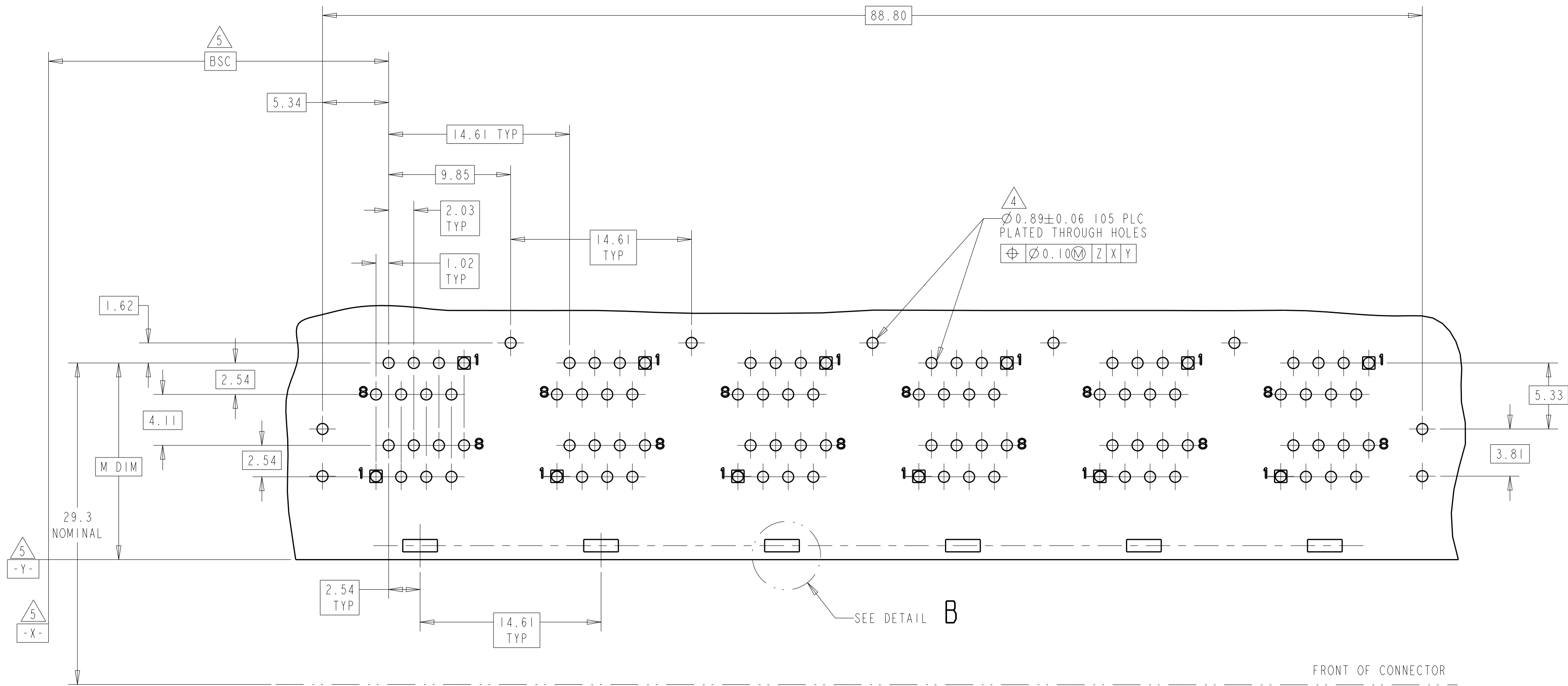
LOC		DIST		REVISIONS					
AA		00		DESCRIPTION			DATE	DWN	APVD
		P	LTR						
			-	SEE SHEET 1			-	-	-



ATCA PANEL AND
PRINTED CIRCUIT BOARD LAYOUT
SCALE 3:1



AMC PANEL AND
PRINTED CIRCUIT BOARD LAYOUT
SCALE 3:1



DETAIL B
SCALE 8:1
PLATED PADS REQUIRED FOR
1888508-2 (PRODUCT WITH
GROUNDING CLIPS)
6 PLC

THIS DRAWING IS UNPUBLISHED. IT IS THE PROPERTY OF TYCO ELECTRONICS CORPORATION. IT IS TO BE USED ONLY FOR THE PURPOSES SPECIFIED. IT IS TO BE RETURNED TO TYCO ELECTRONICS CORPORATION IF IT IS NOT RETURNED TO THE ORIGINAL SOURCE. IT IS TO BE DESTROYED IF IT IS NOT RETURNED TO THE ORIGINAL SOURCE.				DWN A.MAYER 25OCT2006	Tyco Electronics Corporation Harrisburg, PA 17105-3608			
DIMENSIONS: mm				CHK J.WESTMAN 25OCT2006	NAME STACKED MODULAR JACK ASSEMBLY, 2 X 6, 8 POSN, RJ45, SHIELDED, PANEL GROUND, OFFSET, CAT 5			
TOLERANCES UNLESS OTHERWISE SPECIFIED: 9 PLC ± 1 PLC ±0.13 5 PLC ± 4 PLC ± ANGLES ±1°				APVD S.FICKLINGER 25OCT2006	SIZE A1100779			
MATERIAL SEE NOTE 1				PRODUCT SPEC 108-1854	CAGE CODE C=1888508			
FINISH SEE NOTE 1				APPLICATION SPEC 114-2160	RESTRICTED TO CUSTOMER DRAWING			
				WEIGHT -	SCALE 4:1			
				SHEET 2 OF 2				
				REV C				